

L Number	Hits	Search Text	DB	Time stamp
71	4	5399804.URPN.	USPAT	2003/02/04 13:18
94	53	4714952.URPN.	USPAT	2003/02/04 13:20
95	4138	((decoupling decoupled flat) near capacitor)	USPAT; US-PGPUB; EPO; JPO	2003/02/04 13:24
96	2591	((decoupling decoupled flat) near capacitor)) and (die chip (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO	2003/02/04 13:25
97	264	((decoupling decoupled flat) near capacitor)) and (die chip (integrated adj circuit)) and (leadframe (lead adj frame))	USPAT; US-PGPUB; EPO; JPO	2003/02/04 13:26
98	216	((decoupling decoupled flat) near capacitor)) and (die chip (integrated adj circuit)) and (leadframe (lead adj frame)) and (ground grounding)	USPAT; US-PGPUB; EPO; JPO	2003/02/04 13:26
99	26	((decoupling decoupled flat) near capacitor)) and (die chip (integrated adj circuit)) and (leadframe (lead adj frame)) and (ground grounding) and ((die adj pad) (mounting adj area))	USPAT; US-PGPUB; EPO; JPO	2003/02/04 13:51
100	138	((decoupling decoupled flat) near capacitor)) and (die chip (integrated adj circuit)) and (leadframe (lead adj frame)) and (ground grounding) and ((die chip mounting) near1 (pad area))	USPAT; US-PGPUB; EPO; JPO	2003/02/04 13:52
101	112	((decoupling decoupled flat) near capacitor)) and (die chip (integrated adj circuit)) and (leadframe (lead adj frame)) and (ground grounding) and ((die chip mounting) near1 (pad area)) not ((decoupling decoupled flat) near capacitor)) and (die chip (integrated adj circuit)) and (leadframe (lead adj frame)) and (ground grounding) and ((die adj pad) (mounting adj area))	USPAT; US-PGPUB; EPO; JPO	2003/02/04 13:52
102	64	((decoupling decoupled flat) near capacitor)) and (die chip (integrated adj circuit)) and (leadframe (lead adj frame)) and (ground grounding) and ((die chip mounting) near1 (pad area)) not ((decoupling decoupled flat) near capacitor)) and (die chip (integrated adj circuit)) and (leadframe (lead adj frame)) and (ground grounding) and ((die adj pad) (mounting adj area))) and adhesive	USPAT; US-PGPUB; EPO; JPO	2003/02/04 13:54
103	57	((decoupling decoupled flat) near capacitor)) and (die chip (integrated adj circuit)) and (leadframe (lead adj frame)) and (ground grounding) and ((die chip mounting) near1 (pad area)) not ((decoupling decoupled flat) near capacitor)) and (die chip (integrated adj circuit)) and (leadframe (lead adj frame)) and (ground grounding) and ((die adj pad) (mounting adj area))) and adhesive and (base pcb substrate (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO	2003/02/04 13:55